



喬訊電子工業股份有限公司
 CHYAO SHIUNN ELECTRONIC INDUSTRIAL LTD.
 7FL., NO.17, LANE 3, SEC.1 CHUNG CHENG EAST RD.,
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Type Document	Product Specification	Revised / Edition	C
Date Issued	2012/06/20	Data Revised	2013/08/02
Subject: JS-1288S-XX JS-1288S-T JS-1289S-XX JS-1289SR-XX Pitch 1.25mm SMT Series Wire to Board Connector			Issued By: Engineering Dept.

This specification is referred to the 1.25mm SMT series wire to board connector.

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REV. (版次)	Revision Record (改版變更原因)	Date(日期)	EC No
C	Add to item 6.5 locking strength (增列6.5項卡榫拔出規格)	2013/08/02	EC2013-08-002



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1.0 Product Name/Part Number & Drawing Number:

Product Name		Part Number	Drawing Number
Crimp Terminal		JS-1288S-T	JS-1288S-T
Housing		JS-1288S	JS-1288S-XX
Wafer	Straight	JS-1289S	JS-1289S-XX
	Right Angle	JS-1289SR	JS-1289SR-XX

Note: (xx) The number of the circuits.

2.0 Construction/Dimensions/Material & Surface Finish:

Part Name		Material	Surface Finish
Crimp Terminal		Phosphor Bronze	Gold-Plated
Housing		PBT	UL 94V-0
Wafer	Contacts	Phosphor Bronze	Tin Plated
	Solder Tab	Brass	
	Base	PA9T	UL 94V-0
	CAP	PA9T	UL 94V-0



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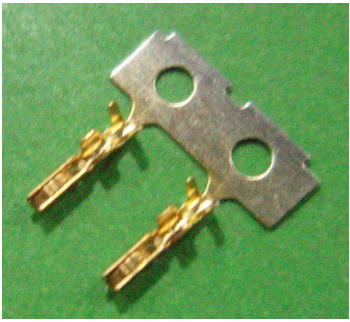
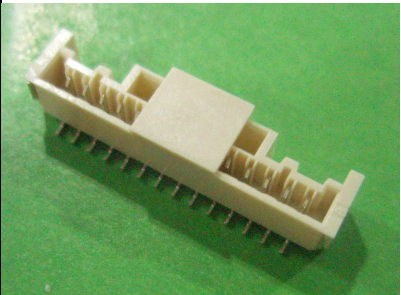

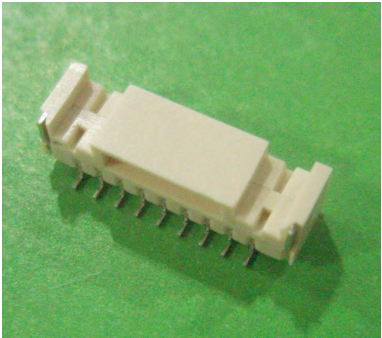
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3.0 Characteristic:

Item		Standard	
3.1	Rated Current	1A AC/DC (With AWG #26 is applied)	
3.2	Rated Voltage	50V AC/DC	
3.3	Ambient Temperature Range	Operating Temp.: -25~+85 ; Including 30°C Terminal Temperature Rise at rated Current . Storage temp.: -25~+85 ;	
3.4	Applicable Wire	3.4.1	Conductor Construction Size: AWG #30~#26
		3.4.2	Wire Insulation O.D.: 0.8mm~1.0mm
3.5	Applicable Printed Circuit Board (PCB)	3.5.1	SMT Layout: 1.25 ±0.05 mm per Pitch
		3.5.2	SMT Layout: 0.6±0.05X1.7±0.1 mm for Pin Post
		3.5.3	SMT Layout: 1.0±0.1X2.7±0.1 mm for Ear Buckle

4.0 Specimen:

Part Name/ Part Number/ Picture or Photograph			
Crimp Contact JS-1288S-T		Wafer Straight JS-1289S-XX	
Housing JS-1288S-XX		Wafer Right Angle JS-1289SR-XX	



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5.0 Applicable Standards:

MIL-STD-202 Methods by test of connectors for electronic equipment.
 EIA 364 Testing method for electrical connectors.

6.0 Mechanical Performance:

Item		Test Condition	Requirement
6.1	Insertion & Retention Force	Insert and withdraw with connectors at the speed rate of 25mm/minute. (EIA 364-13) (A housing lock shall be removed for the measurement.)	Refer to paragraph 9.1
6.2	Crimp Tensile Strength(Axial)	Pull out the cable from contact terminal at the speed rate of 25±6mm/minute.	AWG#26 size wire 2.0Kgf min.
			AWG#28 size wire 1.0Kgf min.
			AWG#30 size wire 0.5Kgf min.
6.3	Contact Retention Force (in Housing)	Axial pullout force on the terminal in the housing at the speed rate of 25 ± 6 mm per minute.	0.7Kgf min.
6.4	Post Retention Force (in Base)	Axial pullout force on the square pin in the base at the speed rate of 25 ± 6 mm per minute. (EIA 364-29C)	0.3Kgf min.
6.5	Locking Strength	A socket housing and a header shall be mated. And then, the load shall be applied between them. The load to come them off each other shall be measured. (Testing speed: 1~ 5 mm/sec.)	2, 3 circuit 1.02 Kgf min.
			4 to 6 circuit 1.22 Kgf min.
			7 to 9 circuit 1.53 Kgf min.
			10 to 15 circuit 2.04 Kgf min.



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7.0 Electrical Performance:

Item	Test Condition	Requirement
7.1 Contact Resistance	A maximum voltage of 20mV and a maximum current of 10mA are applied to the Mate connectors. (EIA 364-23)	Contact Resistance: 30 milliohms Max.
7.2 Current Continuity	Each circuit of the connector shall be connected in series continuity meter shall detect current discontinuity longer than 1 microsecond during the vibration test.	No discontinuity current is longer than 1 microsecond.
7.3 Insulation Resistance	Apply 250V D/C to any two adjacent contacts to measure the insulation resistance. (EIA 364-21)	Insulation Resistance: Initial 100 megohms Min.
7.4 Withstanding Voltage	Apply 500V A/C (rms) for 1 minute and the leakage current shall not exceed 0.5mA to the adjacent terminal and ground of the Mate connectors. (EIA 364-20)	No breakdown or flashover.



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8.0 Environmental Performance:

Item	Test Condition	Requirement
8.1	Vibration Frequency: 10~55~10 Hz/minute. Amplitude: 1.5 mm P-P. Direction: 1. Axis of up and down. 2. Axis of right the left. 3. Axis of front and back. Period: 2 hours for each direction. (EIA 364-28A-23)	Initial Contact Resistance : 30 milliohms Max. (After the test) Contact Resistance: 50 milliohms Max. No discontinuity current is longer than 1 microsecond.
8.2	Humidity Steady State Temperature: 40±2°C. Humidity: 90%~95% (RH). Period: 96 hours continuously. (EIA 364-31)	(After the test) Contact Resistance: 50 milliohms Max. (After the test) Insulation Resistance: 100 Megohms Min. (After the test) Withstanding Voltage : No breakdown or flashover
8.3	Thermal Shock One Cycle Consists Of: -55 +0/-3°C for 30 minutes. → Room Temp.5 minutes 85+3/-0°C for 30 minutes. → Room Temp.5 minutes Total Cycles: 5 Cycles. (EIA 364-32)	Same as paragraph 8.2



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Item		Test Condition	Requirement
8.4	Heat Aging	Temperature: 85±2°C. Period: 96 hours continuously. (EIA 364-17)	Contact Resistance: 50 milliohms Max. after the test.
8.5	Salt Spray	Temperature: 35±2°C. Density: 5 % in weight. Period: Terminal or contact (Stamping after tin plated for 8 hours) ; Terminal or contact (Stamping before tin plated for 48 hours) (EIA 364-26)	(After the test) Contact Resistance: 50 milliohms Max
8.6	Solder Ability	Solder Temperature: 245 ± 5°C. Immersion Period: 3±0.5 Seconds Method : 1.5mm From Square Pin Tip. (EIA 364-52)	Solder entirely 95% of immersed area must show no voids or pinholes.



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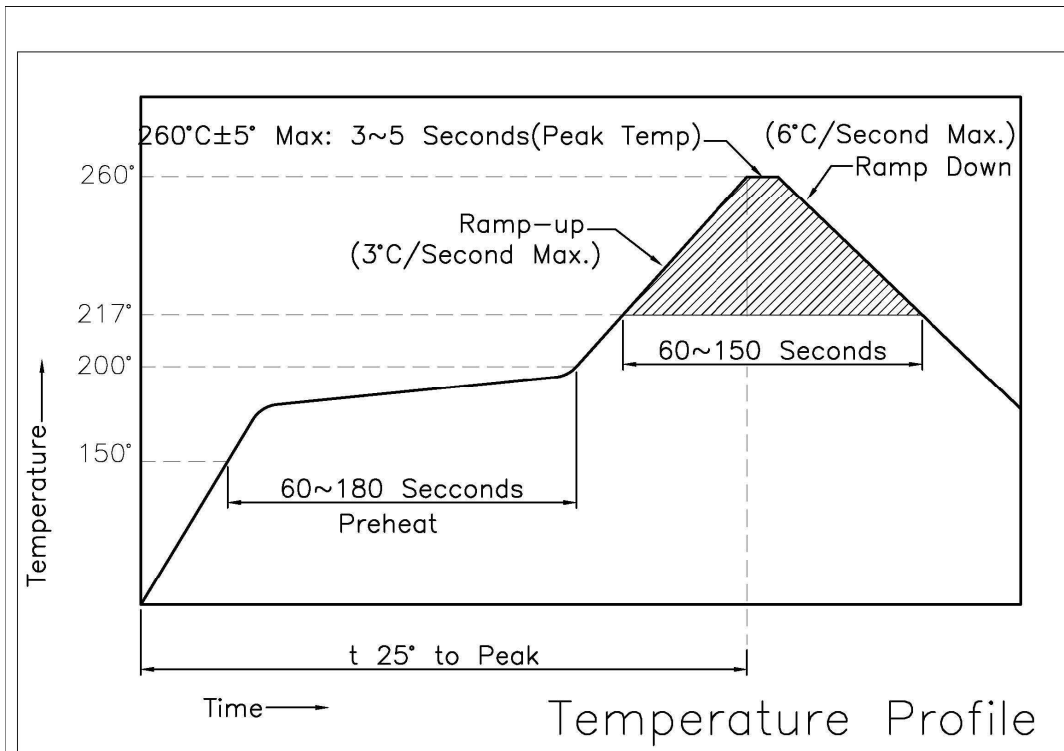


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Item	Test Condition	Requirement
8.7	Resistance To Soldering Heat By reflow soldering: Refer to Temperature Profile 8.8.1 By soldering iron: 350 ± 5°C 3±0.5 Seconds. Method : 0.5mm From Terminal Tip and Solder Tab Tip	Not deformation or damage.

8.7.1 Temperature Profile:





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9.0 Insertion Force (I.F.) & Retention Force (R.F.)

9.1 Requirement:

No. Of Circuits	AT INITIAL		AT 30TH	No. Of Circuits	AT INITIAL		AT 30TH
	I.F. (MAX)	R.F. (MIN)	R.F. (MIN)		I.F. (MAX)	R.F. (MIN)	R.F. (MIN)
02	1.7	0.05	0.05	09	2.4	0.40	0.40
03	1.8	0.10	0.10	10	2.5	0.45	0.45
04	1.9	0.15	0.15	11	2.6	0.50	0.50
05	2.0	0.20	0.20	12	2.7	0.55	0.55
06	2.1	0.25	0.25	13	2.8	0.60	0.60
07	2.2	0.30	0.30	14	2.9	0.65	0.65
08	2.3	0.35	0.35	15	3.0	0.70	0.70

(Kg/f)

10.0 Caution : Parts are made of hydrophilic Polyamide 9T and apt to absorb moisture. Once the vacuum-packing unpacked, please keep parts in the environment of **temperature < 30°C/ humidity < 60% RH**, and send to re-flowing **within 72 hours** to prevent parts blistered or deformed during soldering.

11.0 Remark: Any change or revision for the product specification will not be announced in advance. Please contact our sales representative for the latest information.



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Title of Document	HANDLING MANUAL		Issued By: Engineering Dept.
Title Subject	Pitch 1.25mm Wire to Board Connector JS-1288S-T JS-1288S JS-1289S JS-1289SR		

This manual describes important and required points of handling about connector . Be sure to read this manual thoroughly before using connector.

*此操作手冊係說明連接器使用時必須注意的重點事項，
務必詳加閱讀內容之後，再行使用本產品*

1.0 Instructions on mating crimped terminal to plug housing Following defines the terminal insert and repair

鉗壓端子與插頭組裝之說明，以下解說端子的嵌入過程

1.1 Terminal Mating 端子組裝

1.1.1 Hold the housing on the top/bottom surface 握持膠座上下兩面。

※ When you hold the wire at a further position, the wire would bend easily, making it difficult to insert the terminal. 當握持電線距鉗壓部位過遠的位置，電線容易彎曲下垂，使得它不易將端子嵌入膠座。

1.1.2 Please hold the cable at a 10mm distance from the crimped section.

請在距離鉗壓處 10mm 的位置握住電線。(see figure 1.1.2)

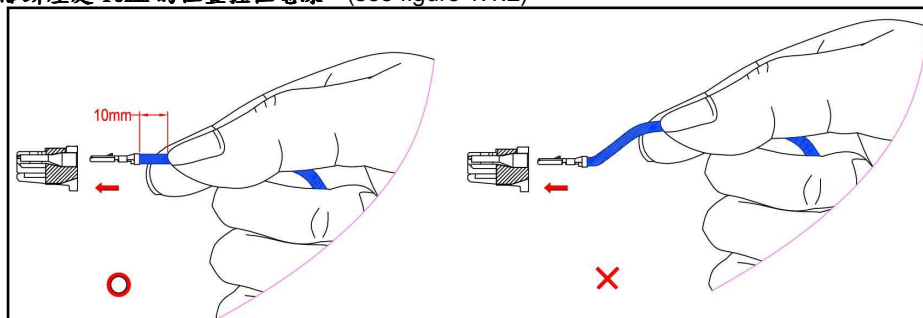


figure 1.1.2

※ The value (10mm) is a reference. It changes regards to the wire size and Material. Please confirm the best position before starting the insertion.

10mm 僅供參考，視電線的尺寸大小及材質而有所改變，並在嵌入前確認合適的位置。

※ Please crimp the terminal using the specified height and width.

(Refer to crimp specification JS-1288S-T)

端子鉗壓請依照規範之高度與寬度使用(參考 JS-1288S-T 端子壓著規格書)

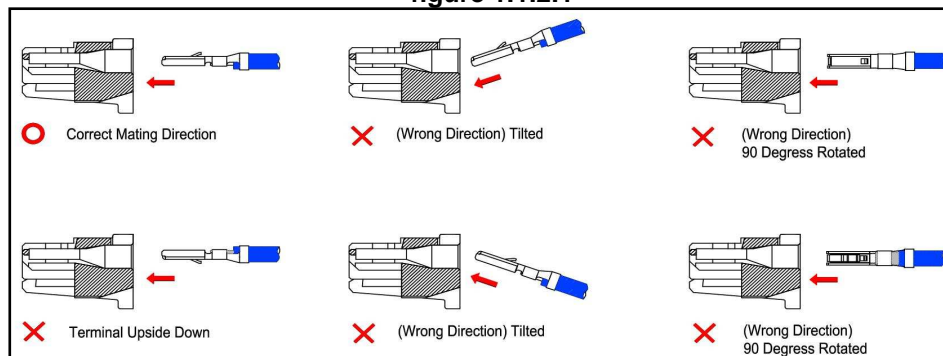
※ When insertion cannot be done smoothly, do not force the terminal to mate the connector. Please reconfirm if there is no deformation in the plastic or the terminal and re-insert.

當端子嵌入膠座不順暢，切勿使力將端子嵌入膠座，請先確認端子或膠座是否變形損壞然後再行嵌入組裝。

※ Please be careful on the direction of the terminal insertion. When the terminal is inserted in the wrong direction, it could lead to terminal deformation or plug housing breakage. (see figure 1.1.2.1)

請於端子嵌入膠座的同時仔細確認其方向，當端子嵌入方向錯誤，會導致端子變型損壞以及膠座破損。

figure 1.1.2.1





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- ※ These crimped contacts should be absolutely straight and, without the use of extreme force, inserted in one operation into the contact cavities until a “click” is audible.(see figure 1.1.2.2) (300g~500g forces is recommended)
施予適度的力量將端子不偏不倚的嵌入膠座，直到端子彈片卡合定位聽見“喀察”聲為止。
(建議嵌入力 300 克~500 克 之間)。

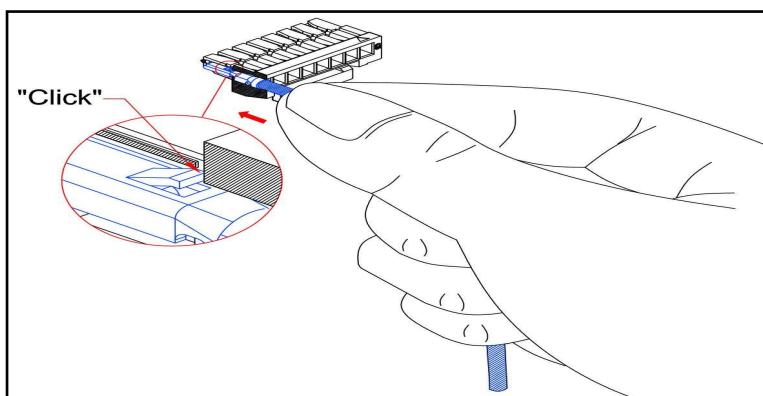


figure 1.1.2.2

- 1.1.3 Confirm if the terminal is inserted correctly by pulling the terminals with little force (100g). Do not pull hard.

當端子嵌入膠座之後，試著以少於 100g 的力量輕微拉動端子，切勿過度使力拉動端子，以此方式確認端子嵌入位置是否正確。

- ※ Misalignment of the crimped contacts should be avoided because of possible bending of the retention springs, and therefore impaired contact retention in the contact cavity. (see figure 1.1.3)
端子嵌入膠座其彈片卡合未達定位，可能使彈片變形，進而導致端子拔出力大幅衰減。

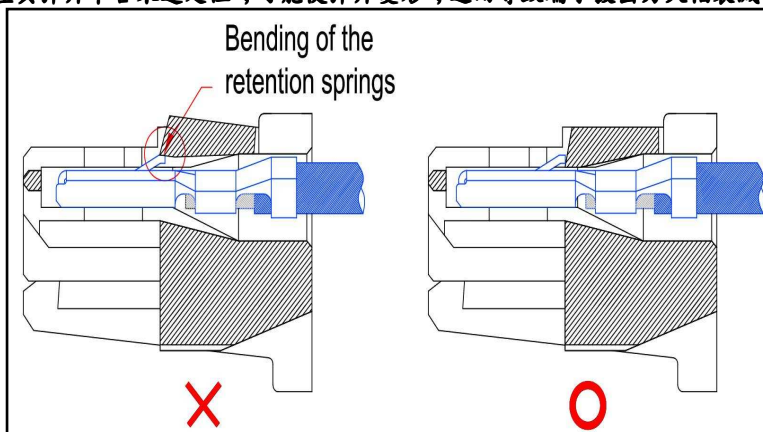


figure 1.1.3

- 1.1.4 When checking after terminal insertion, do not pull or bend the wire too much. The unanticipated force to the connector may lead to contact failure.

當確認端子已確實嵌入膠座，勿過度拉扯或彎曲電線，可能使電流導通失效。

- 1.1.5 Please use the defined mating connector when you check the continuity. Mating with the wrong connector may lead to terminal deformation and contact failure.

組裝前請先行確認所搭配之連接器膠座，是否為同款系列之產品，錯誤搭配不屬同款的連接器，將導致端子變形損壞，電流導通失效。



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2.0 SMT Handling Precautions 使用表面黏著須知：

2.1 Reflow Soldering Method 迴焊使用方法：

Soldering should be conducted at the temperature below the temperature profile shown in product Specification as item of “Resistance to soldering heat”

迴焊所適用溫度條件，參照規格書“焊錫耐熱性”項目中所示溫度曲線圖。

Though recommended reflow temperature condition varies depending on solder paste to be used, evaluate and find adequate condition before production.

迴焊建議溫度僅為參考，溫度條件的變化亦取決於錫膏的使用，視實際使用需求而作調整。

Depending on the soldering condition, solder and flux wicking may occur on this connector. Check no problem in customer soldering condition before the use.

錫膏毛細現象，攸關迴焊條件良窳，有可能造成連接器使用時溢錫、爬錫之發生。

迴焊所需具備之條件，應先確認無誤之後，再行使用本產品

Considering Handling of this connector in mating operation, tenacious heat-resistant resin is used for this connector. But ‘Blister’ may generate on the outer surface of the housing during the process of reflow soldering, depending on the condition of moisture absorption of the housing and the condition of reflow soldering. However, because ‘blister’ is not caused by decomposition of resin, it does not affect the performances of the connector.

連接器所採用具剛性且耐高溫之塑膠，經迴焊製程可能會在連接器表面產生氣泡，其生成的原因源自於塑膠過度吸濕以及迴焊製程條件優寡，然而氣泡並不會對於塑膠產生侵蝕的作用，而且就連接器組裝使用功能性而言並不影響。

There is no influence in the product performance though discoloration might be generated in the resin according to reflow condition.

迴焊製程亦可能引起塑膠色澤變化，但不影響產品功能。

2.2 About whisker growth prevention for this product 關於避免錐鬚的生成

The Lead-Free plating of this product has been performed by re-flow matte-tin or gold plating which ensures maximum effectiveness for retarding whisker growth. It fully comply with JEDEC-JP002-(Current Tin-Whiskers Theory and Mitigation Practices Guideline.)

此產品經採用無鉛鍍霧錫或鍍金施行於迴焊製程，已確認其對於延緩錐鬚生長可發揮最大效用。此方式完全符合 JEDEC-JP002 規範（當前通用的錐鬚理論和緩解實例指導方針）。

2.3 Connector Placement 連接器定位

Machine placement of the connector is recommended due to the inherent difficulty of manually placing fine-pitch connectors. The top surface of the connector housing has a flat area in the center to facilitate vacuum pick-up and handling. To avoid damage, the connectors should be picked up directly out of the embossed-tape packaging by the pick-up device. The placement machine is used to position the connectors to minimize the possibilities of damage that could result from improper handling.

細距連接器經由手工置件定位極富難度，建議以機械方式置件定位取代，機械方式置件定位，可降低因操作不當而導致連接器損壞的情形發生。連接器表面平坦處且位於整體中心位置，較易於真空取件作業。真空取件應以垂直起降方式，將零件由包裝載帶取出，並避免損壞連接器。

Placement of the connectors may be done by hand; however, extreme caution must be used when handling connectors to prevent deformation and contamination of the solder tines and hold-downs. 某些情況下可能以手工置件定位，尤特別謹慎避免連接器沾污、以及過度施力損壞連接器金屬導體末端焊錫區域。

2.4 Coplanarity 金屬導體與焊錫區域共面度：

Optimally, the connector contact solder tines should be centered on the PC board Pads. however, misregistration is permissible for some performance classifications.(See Figure 2.4)

連接器金屬導體安放之最佳位置應產落於印刷電路板各相對應腳位之焊錫區域之中心線，然而對於有些效能特性之分類，可允許對位落差。



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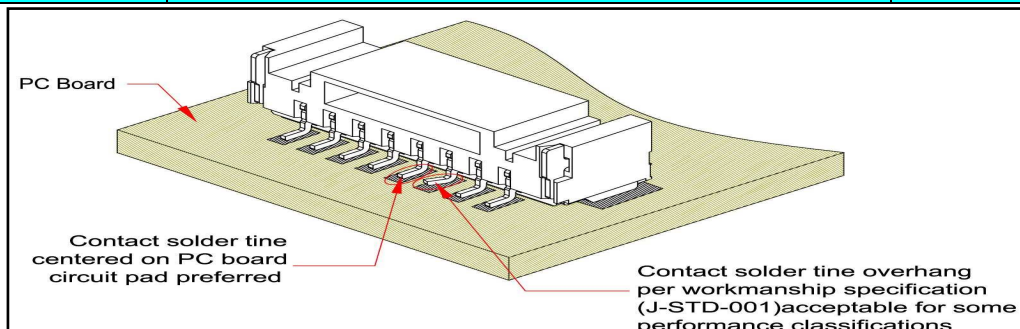


Figure 2.4

2.5 Solder Iron Method 手焊使用方法：

When soldering or re-soldering connector on PC board, below the temperature shown in product Specification as item of "Resistance to soldering heat"

電路板上連接器使用手工焊錫或者是重焊，所適用溫度條件，參照規格書“焊錫耐熱性”項目中所建議溫度。

Do not apply external force by pressing soldering iron tip on contact solder tail part.

切勿以過度的力量，將烙鐵尖端重壓導體末端焊錫區域。

If done, dismount and exchange connector. Do not reuse dismounted connector.

如以手焊方式卸除連接器應將其更換，切勿重覆使用已卸除之連接器。

3.0 Recommended insertion 連接器嵌入組合建議使用方式

3.1 Set the plug and the receptacle housing assembly in the correct direction and Insert the receptacle housing straightly in the plug housing. Please hold the both sides of the plug housing and push until the connectors lock completely. After mating, confirm the thumb latch is in the correct location.

將插頭循正確的方位，不偏不倚地嵌入互配之一端。請握持插頭兩側往前推直到與插座完全卡合為止。

組裝完成之後，確認活動卡榫是否在正確位置。(see figure 3.1)

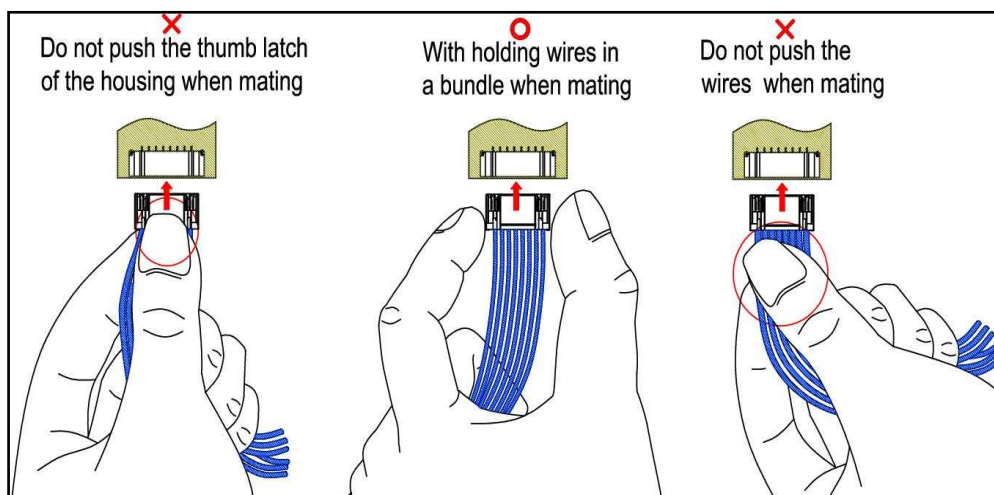


figure 3.1

※ Do not push the thumb latch of the housing when mating. This prevents the normal movement of the locking where the lance slips over the thumb latch. This leaves excessive load to the housing and end as a damage. (see figure 3.1)

連接器作嵌入組裝的同時，切勿按壓活動卡榫，會使卡榫承受額外的負載，進而影響活動卡榫在自由狀態下自行到位的卡合功能，甚至於造成卡榫結構損壞。



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3.2 This connector is designed for polarizing. Please be careful on the direction of the housing insertion. (see figure 3.2)

此款連接器設計具有防止逆向嵌合之功能，請務必於嵌入線端連接器的同時確認其方向正確與否。

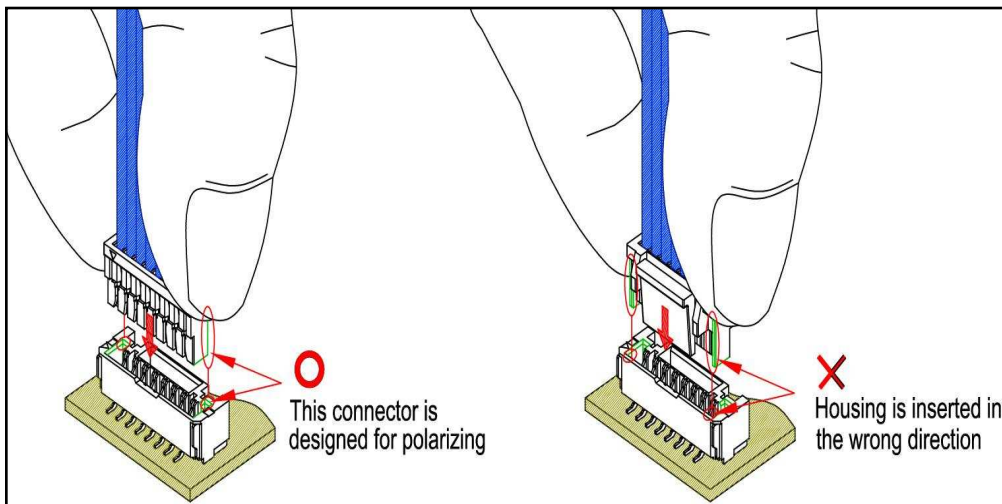


figure 3.2

3.3 This connector is designed to prevent pin damage due to tilted insertion. however, please keep in mind that tilted insertion could widen the side walls on the mold which could lead to lock force decrease, especially when the number of circuits is big. (see figure 3.3)

此款連接器之設計其功能主要防止傾斜嵌入造成 Pin 針變形，請務必謹記過於傾斜的嵌入會使膠座側壁結構撐大，導致活動卡榫活動力降低，尤其多 Pin 位連接器愈加明顯。

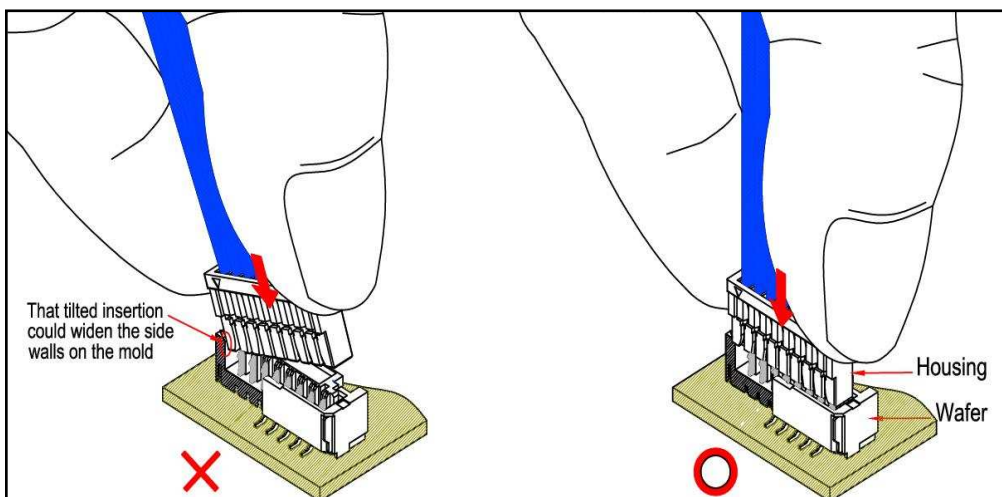


figure 3.3

※ In case the insertion is not smooth, please confirm if there is no damage to the connector nor the pin, and re-insert.

如嵌入組裝不順暢，請先行確認連接器以及 Pin 是否有損壞情形之後再作嵌入組合



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- ※ Mated with audible "Click" voice is added mating assurance. Connectors shall be used in the condition in which incomplete mating would not occur.
連接器經組合後必須完全密合才可進行導通使用，當嵌入組合卡榫發出'喀察'聲音，即可確認其已到達定位。

4.0 Recommended removal 卸除連接器建議使用方式

4.1 Hold the wires together, attach your fingers to the side without the latch and push the thumb latch on the sides. When confirmed that the latch is released, pull the connector upwards. (see figure 4.1)

握持整組電線，並將手指輕貼於活動卡榫按壓部位然後將邊上的活動卡榫向下推。

當確定活動卡榫完全鬆脫時，將連接器卸下。

- ※ When removing the latch, be sure to unlock completely. This connector is designed so the connector does not unlock when the thumb latch is in effect. When you try to pull the connector with the thumb latch is in effect, the connector will break. (see figure 4.1.2)

卸除活動卡榫的同時，確認活動卡榫是否完全脫離，此款連接器之設計其功能主要在卡榫卡合之後不易鬆脫，而且在活動卡榫未卸除之前，試圖拔出連接器將導致其破損。

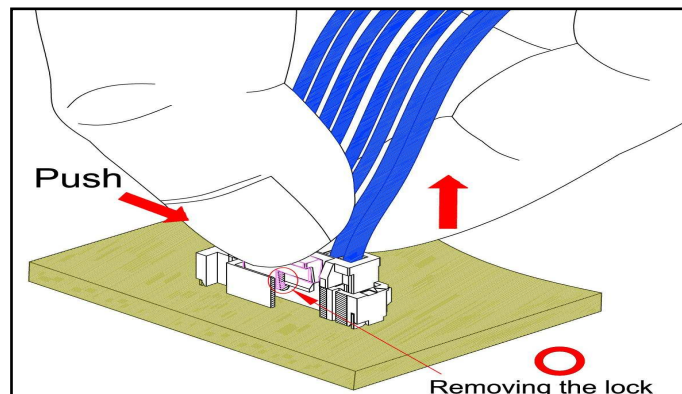


figure 4.1

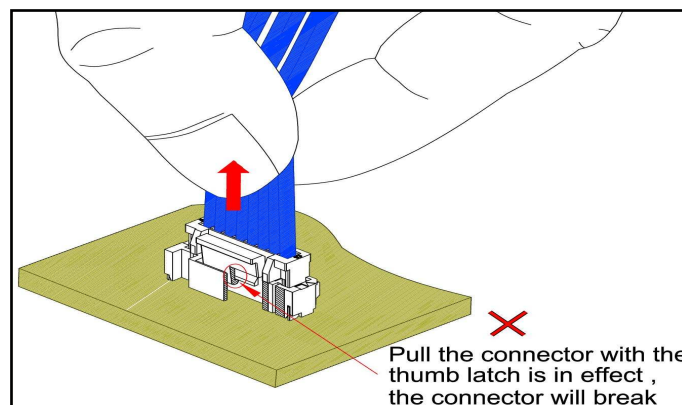


figure 4.1.2



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4.2 Please hold all wires equally to prevent excessive force on certain wires. excessive force could lead to damage. (see figure 4.2)

請將握持電線的力量均勻分佈於每條電線，避免過度施力於某幾條電線，施力過度可能導致損壞。

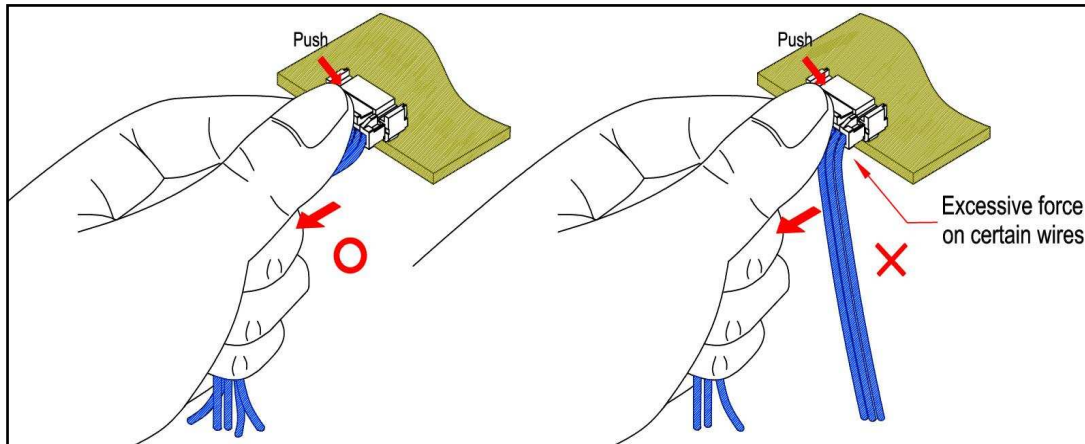


figure 4.2

5.0 Handling of wire after mounting connector on PC Board:

連接器於電路板裝載完成，後續線材配置方式

5.1 Conduct wire handling carefully so that tension stemmed from wire bending is not loaded. Provide space above connector in order to form wire by bending and do not apply tension to connector as below. (see figure 5.1)

電線承受過度的彎折會引起緊繃的張力，因此電線所處的位置應謹慎妥善的配置。連接器周圍應具備足夠空間可供電線作適當彎折，以避免其產生張力承載於連接器。

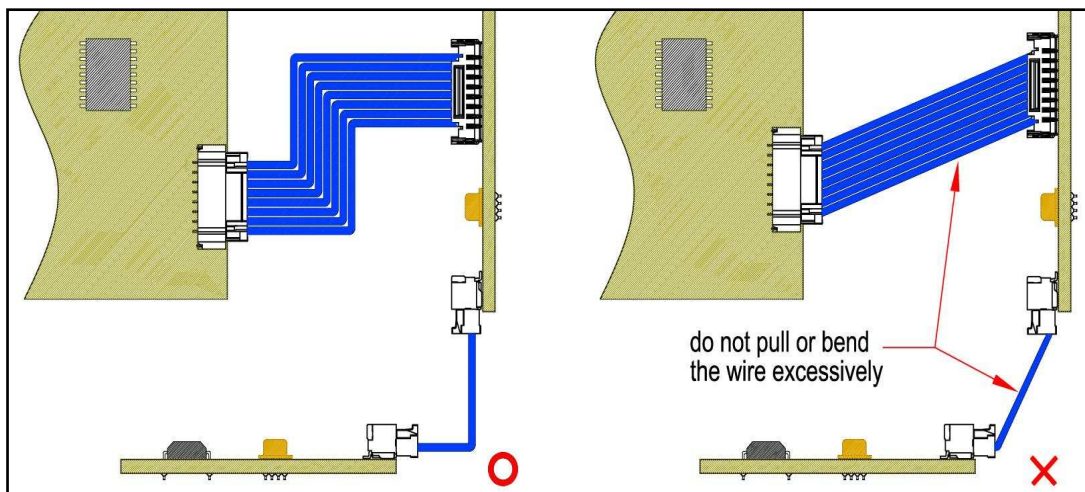


figure 5.1

Reviewed: J.M.Chang **Approved:** Peter Chang **Verified:** Indiana Huang